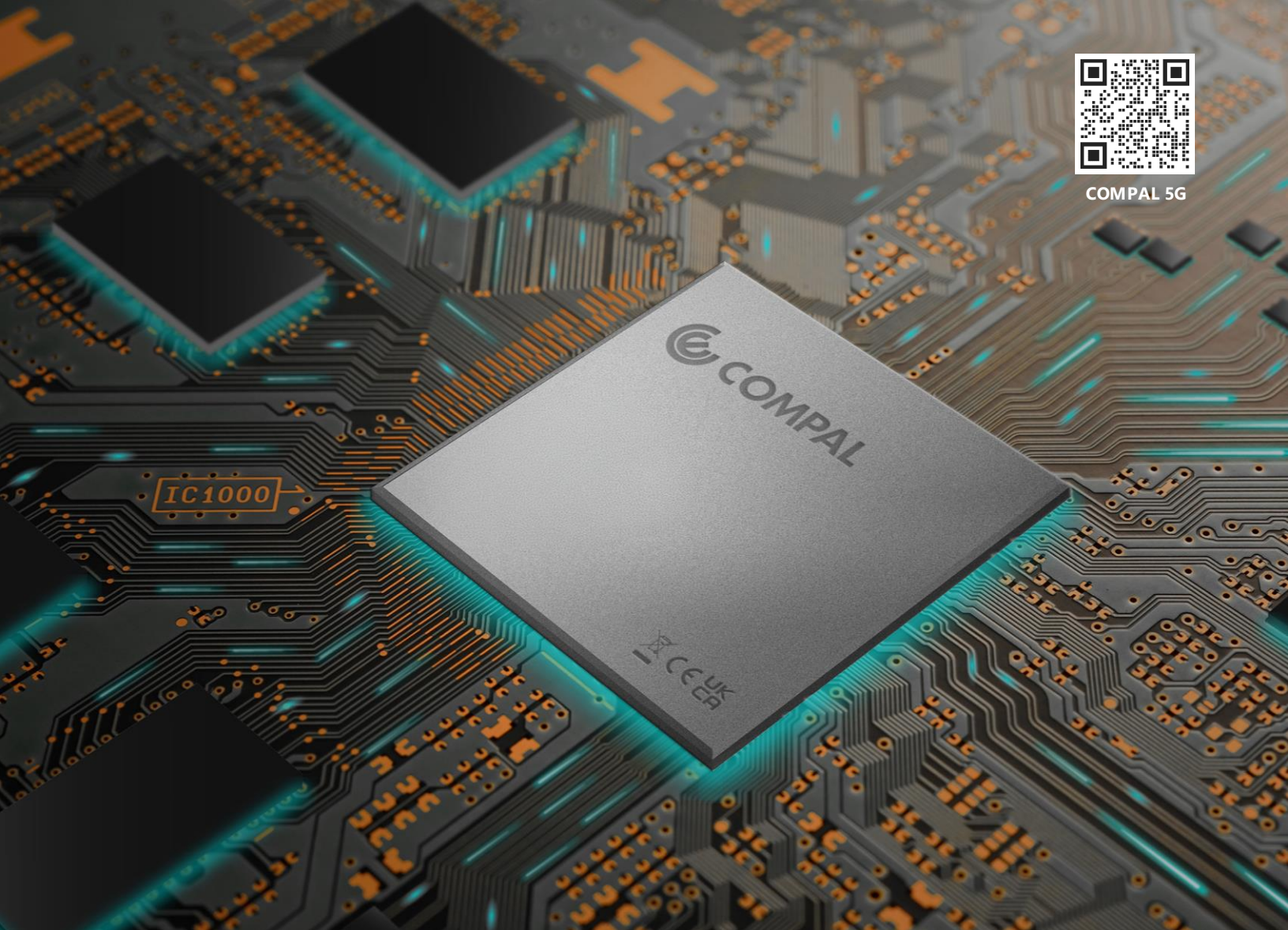




COMPAL 5G



Driving IoT, AI, and 4G/5G/6G Innovation Compal WWAN Modules Lead the Way

As a tier-one leader in ODM/EMS, Compal delivers cutting-edge technologies and solutions for IoT, AI, and 5G, offering innovation and sustainability via its advanced 4G/5G module and UE portfolio.

Compal's 4G/5G modules and UE product line, including 5G eMBB, 4G-Advanced, Cat-1bis, Cat-M, 4G/5G CPEs, MiFi, and dongles, deliver ultra-fast speeds up to 7.5Gbps with low latency. Supporting Sub-6GHz, mmWave bands, and SA/NSA networks, these Qualcomm and MTK-powered solutions ensure scalability, robust connectivity, and sustainability across IoT, industrial, consumer, and enterprise applications.

Compal integrates circular economy principles to optimize resources, reduce waste, and promote renewable energy, targeting net-zero emissions by 2050.

Join our global channel program to drive innovation and sustainability together with Compal.



FROM VISION TO REALITY

Innovation Empowered

COMPAL5G

4G/5G Module Product

5G eMBB



RXM-G1
SDX55
5G Sub6, Global
M.2 module
30x52x2.3 mm



RXM-G2
SDX62
5G Sub6, Global
M.2 module
30x52x2.3 mm



RXM-G2L
SDX61
5G Sub6, Global
M.2 module
30x52x2.3 mm



RXM-G3
SDX72
5G Sub6, Global
M.2 module
30x52x2.3 mm



RXM-G4
SDX82
5G Sub6, Global
M.2 module
30x 52 x2.3 mm



RXM-G4L
SDX81
5G Sub6,Global
M.2 module
30 x 52 x2.3 mm



RXL-G1
SDX55
5G Sub6, Global
LGA module
30x52x2.3 mm



RXL-N2
SDX62
5G Sub6, NA
LGA module
45x 45 x2.45 mm



RXL-E2A
SDX65
5G Sub6, EU
LGA module
45x 45 x2.45 mm



RXL-N3
SDX72
5G Sub6, NA
LGA module
49x 50 x2.75 mm



RXL-E3
SDX72
5G Sub6, EU
LGA module
49x 50 x2.75 mm



RXL-G4
SDX82
5G Sub6, Global
LGA module
39 x 42 x2.64 mm



RXL-N4A
SDX85
5G Sub6, NA
LGA module
49x 50 x2.75 mm



RXL-E4
SDX82
5G Sub6, EU
LGA module
49x 50 x2.75 mm



RMM-G1
T700
5G Sub6, Global
M.2 module
30x52x2.3 mm



RMM-G1L
T700
5G Sub6, Global
M.2 module
30 x 52 x2.3 mm



RMM-G4
T900
5G Sub6, Global
M.2 module
30x52x2.3 mm



RML-N1
T750
5G Sub6, NA
LGA module
45x 45 x2.65 mm



RML-E1
T750
5G Sub6, EU
LGA module
45x 45 x2.65 mm



RXL-N2
T830
5G Sub6, NA
LGA module
45x 45 x2.65 mm



RML-E2
T830
5G Sub6, EU
LGA module
45x45x2.65 mm



RML-N4
T930
5G Sub6, NA
LGA module
45x45x2.65 mm



RXL-E4
T930
5G Sub6, EU
LGA module
45x 45 x2.65 mm

Mass
Production

Developing

Planned

Smart Transportation

Autonomous Vehicles, Parking
Public Transport Management

Smart Buildings

Smart Grids, Lighting
Energy Management Systems

Smart Environment

Environmental Monitoring
IoT-enabled Smart Homes

Smart Security

City Surveillance
Emergency Response Systems

Smart Healthcare

Telemedicine, IoMT
Smart Ambulance

Smart Retail

Digitalized Stores
Logistics Tracking

5G RedCap



CXM-G3
SDX35
5G RedCap, Global
M.2 module
30x42x2.3 mm



CXC-N3
SDX35
5G RedCap, NA
LCC module
32x29x2.45 mm



CXC-E3
SDX35
5G RedCap, EU
LCC module
32x29x2.45 mm



CMM-G3
T300
5G RedCap, Global
M.2 module
30x42x2.3 mm



CMC-N3
T300
5G RedCap, NA
LCC module
32x29x2.45 mm



CMC-E3
T300
5G RedCap, EU
LCC module
32x29x2.45 mm

4G/4G-Advanced



EXM-G1A
SDX12
4G Cat12, Global
M.2 module
30 x 42 x 2.3 mm



EXC-N1
MDM9207
4G Cat1/4, NA
mPCIe
30x51x5.3 mm



EXC-E1
MDM9207
4G Cat4, EU
mPCIe
30x51x5.3 mm



EXC-T1E
MDM9207
4G Cat4, JP
mPCIe
30x51x5.3 mm



EXC-N1
MDM9207
4G Cat1/4, TW/AU
mPCIe
30x51x5.3 mm



EXC-E1
MDM9207
4G Cat4, NA
LCC
32x29x3.5 mm



EXC-T1
MDM9207
4G Cat4, JP
LCC
32x29x3.5 mm

LPWA



ESM-G1
ALT1250
4G Cat-M, Global
M.2 module
22x42x2.3 mm



EXM-G3
QIM226
4G Cat 1.bis, Global
M.2 module
22x42x2.3 mm



EXM-G4
QCX217
4G Cat 1.bis, Global
M.2 module
22x42x2.3 mm



EXL-N2
QCX216
4G Cat 1.bis, NA
LGA module
23x22x2.5 mm



EXL-E2
QCX216
4G Cat 1.bis, EU
LGA module
23x22x2.5 mm



EXC-N3
QIM226
4G Cat 1.bis, NA
LCC module
16x16x2.5 mm

Mass
Production

Developing

Planned

COMPAL 5G

5G UE

CPE



Scorpion

Qualcomm SDX12
R12, LTE Cat6/12
WiFi 6, 4x4 MIMO



Scorpion Max

Qualcomm SDX62
R16, 5G Sub6 NSA/SA



Fortis

Qualcomm SDX62
R16, 5G Sub6 NSA/SA
WiFi 6, 4x4 MIMO



Citadel

Qualcomm SDX72
R17, 5G Sub6 NSA/SA
WiFi 7, 4x4 MIMO



CoreLink

Qualcomm SDX35
R17, 5G RedCap SA/LTE
WiFi 6, 2x2 MIMO

MiFi



Asgard

Qualcomm SDX55
R15, 5G Sub6 NSA/SA
2.4" LCM, 5300 mAh
WiFi 7, 4x4 MIMO



Valhalla

Qualcomm SDX72
R17, 5G Sub 6 NSA/SA
2.4" LCD+ 5000 mAh
WiFi 6, 2x2 MIMO



Aries

MediaTek T750
R15, 5G Sub 6 NSA/SA
5300 mAh, IP65
WiFi 6, 2x2 MIMO



Aether

MediaTek T830
R16, 5G Sub 6,
Cat20/Cat13
2.4" LCM, 5000 mAh
WiFi 6, 4x4 MIMO



Crown

MediaTek MT8863
R16, 5G Sub 6 NSA/SA
2.4" LCM, 5150 mAh
WiFi 5

Dongle



RediEdge

Qualcomm SDX55,
R15, 5G Sub6 NSA/SA
USB 3.1 Type C



RediLite

Qualcomm QIM226,
R14, 4G Cat 1.bis
USB 2.0 type A



RediGo

Qualcomm SDX35,
R17 RedCap,
5G Sub6 SA/LTE
USB 3.1 TypeC



CapMax

MediaTek T700,
R15, 5G Sub6 NSA/SA
USB 3.1 type C



Caplet

MediaTek T300,
R17 RedCap,
5G Sub6 SA/LTE
USB 3.1 TypeC

Mass
Production

Developing

Planned

4G/5G Module Product



5G eMBB



5G RedCap



4G/4G-Advanced



Cat-1bis/Cat-M

5G UE Product



5G CPE



5G MiFi



5G Dongle



Key Partners

Qualcomm

MEDIATEK

Altair



docomo

OPTUS

Rakuten



Smart

SoftBank

T-Mobile



Telefónica



Telstra

verizon

vodafone

Global Footprint

